

T-4909-AE

40
YEARS
ANNIVERSARY
EDITION

For the past 40 years, Dr. Tresky AG has been perfecting the art of creating die bonding / pick & place systems.

The **T-4909-AE anniversary edition** is a manual, budget sensitive die bonder with superior ergonomic design. As with all of Tresky's products, the **T-4909-AE** incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height. Bonding parameters and sequences, intuitively programmable by an integrated Raspberry PC with touchscreen.

T-4909-AE Application Packages:

- Epoxy
- Eutectic
- Flip-Chip

Force controlled

True Vertical Technology™

Easy to use

MICRO ASSEMBLY

T-4909-AE



TRESKY

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Excellent performance, ergonomically designed and high reliability makes the **T-4909-AE** ideal for small and medium volume production.

APPLICATIONS

Die Attach, Flip-Chip, MEMS, MOEMS, VCSEL, RFID, Adhesive Bonding, Eutectic Bonding,

FEATURES AND OPTIONS

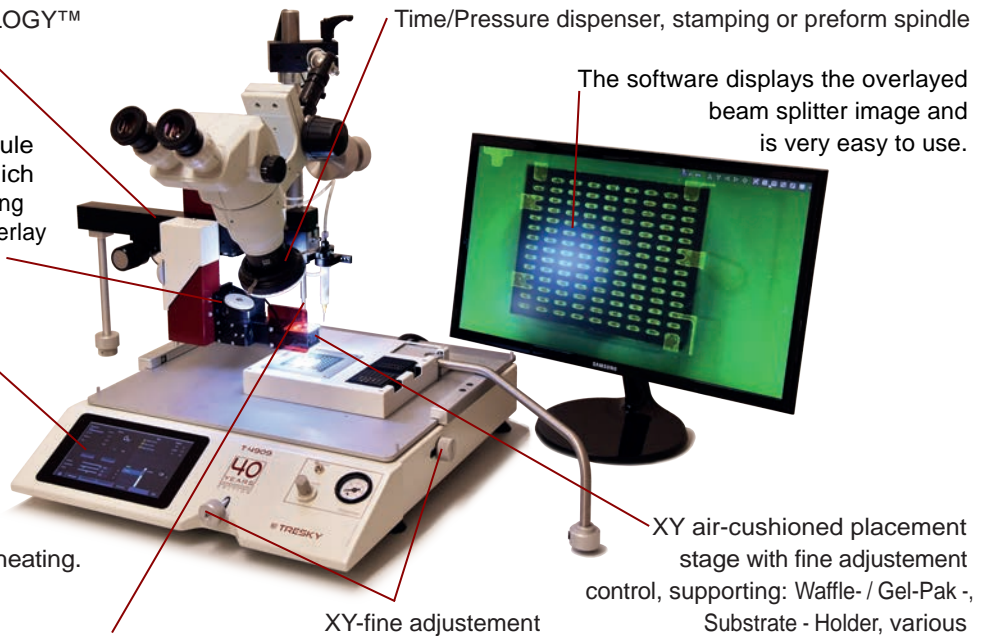
TRUE VERTICAL TECHNOLOGY™ with 95mm Z-movement

FLIP-CHIP ULTRA module is a beam splitter optics, which allows the simultaneous viewing of two objects by an optical overlay (superposition) on the monitor. (Option)

Touchscreen for selection of pick & place, dispensing, stamping, mode. Create and store custom sequence.

E.g.: Pick, dispense and place with automatic start of heating.

Pick & place spindle with force sensor and 360° tool rotation. Optional: with tool heating and Scrub



Time/Pressure dispenser, stamping or preform spindle

The software displays the overlaid beam splitter image and is very easy to use.

XY air-cushioned placement stage with fine adjustment control, supporting: Waffle- / Gel-Pak -, Substrate - Holder, various Heating Plates.

XY-fine adjustment

TECHNICAL DATA

XY- Movement (placement stage):	180mm x 180mm (manual)
Z- Movement:	95mm (manual)
Spindle Rotation:	360° (unlimited)
Bond Force:	20g - 1000g
Placement accuracy:	±10µm (operator/process depending)
Flip-Chip Placement accuracy:	±5µm Option (operator/process depending)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	755mm x 730mm x 500mm
Weight:	33kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

Represented by

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